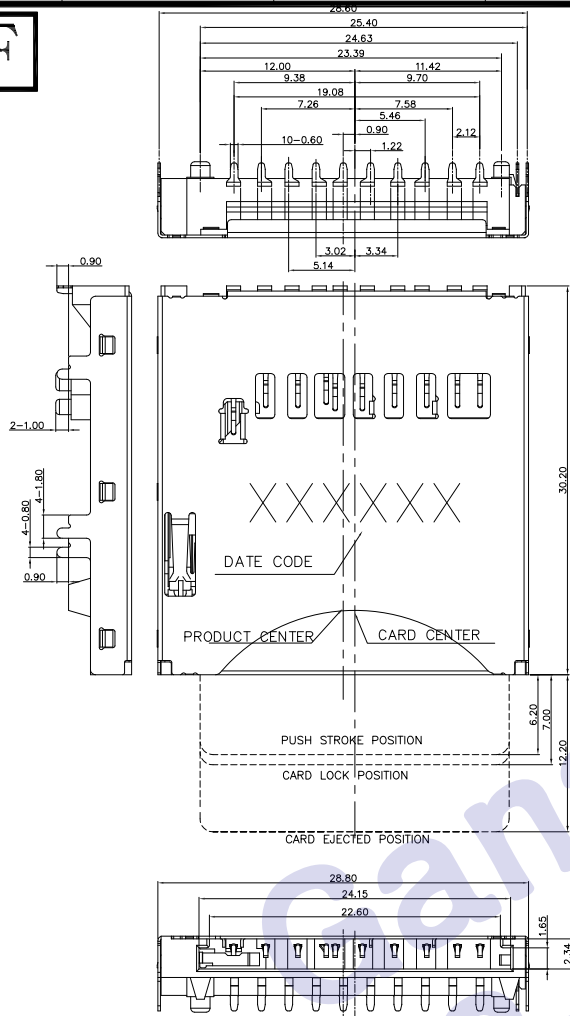
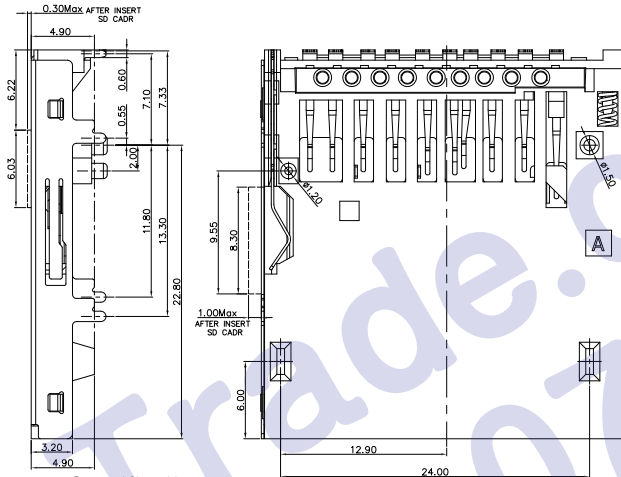


HSF



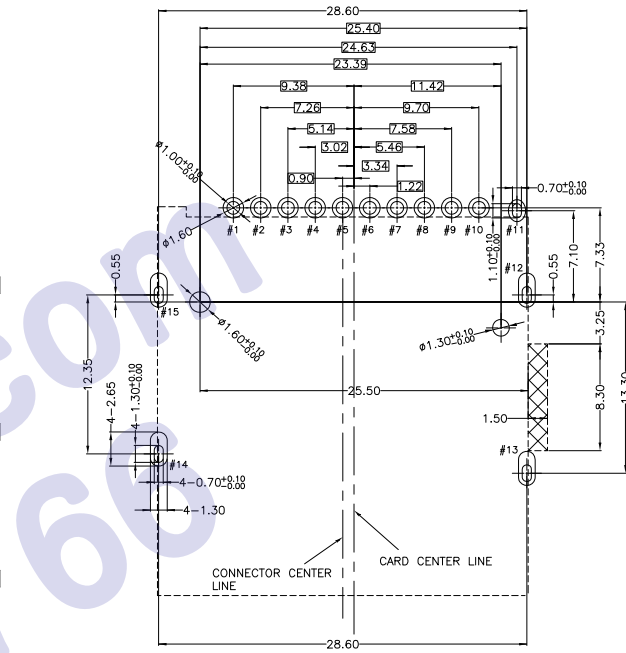
PART.NO.:
TW38-AP402-**

- 42: 功能区镀金1U", 锡脚镀雾纯锡至少100U"
- 43: 功能区镀金3U", 锡脚镀雾纯锡至少100U"
- 44: 功能区镀金5U", 锡脚镀雾纯锡至少100U"
- 45: 功能区镀金10U", 锡脚镀雾纯锡至少100U"
- 46: 功能区镀金15U", 锡脚镀雾纯锡至少100U"
- 47: 功能区镀金30U", 锡脚镀雾纯锡至少100U"



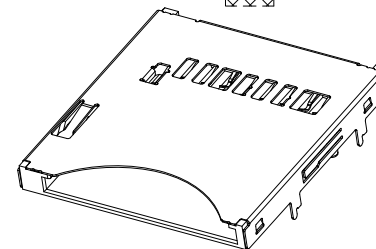
Specification

- *Electrical Characteristics:
Contact Current Rating:0.5 Amperes.
Dielectric Withstanding Voltage:AC500V r.m.s.
Insulation Resistance:1000 MΩ Minimum.
Contact Resistance:100 mΩ Maximum.
- *Environmental:
Operating Temperature:-25°C~+85°C.
- *Mechanical Characteristics:
Mating Cycles:10,000 Cycles Insertion/Extraction
Card Push Insertion/Out Force:1kgf Maximum.
Contact Retention Force:0.15kgf Minimum.
- *Material:
INSULATOR: LCP, RATED UL94V-0,COLOR: BLACK.
CONTACTS: PHOSPHOR BRONZE.
GOLD(SEE P/N) PLATED ON CONTACT AREA,
100u" MIN MATTE TIN PLATED ON SOLDER AREA,
30u" MIN NICKEL PLATED OVER ALL.
SHELL: STAINLESS STEEL.NI 30u"MIN
30u" MIN SOLDERABLE NICKEL PLATED OVER ALL.
SPRING: SWP-B.



RECOMMEND P.C.B LAYOUT TOLERANCE ±0.05

⊗ No component area



Pin Define		
Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DATO
P10	P8	DAT1
P11		W/P
P12		GND
P13		GND
P14		GND
P15		GND

WITHOUT CARD		CARD INSERTED:LOCK		CARD INSERTED:UNLOCK	
W/P #11	GND #12	W/P #11	GND #12	W/P #11	GND #12
C/D #04	VSS1 #05	C/D #04	VSS1 #05	C/D #04	VSS1 #05

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
AO	2014/12/25	NEW		X.X	±0.40		UNIT	mm	TW38-AP402-**
				X.XX	±0.25		SIZE	A4	TITLE:
				X.XXX	±0.15		SHEET	1/1	SD Push H4.90 Conn
				Angle	± 3'		PROJ.		Customer NO.
				DIM	TOL				

HDC电子有限公司

REVERSE TYPE